

ABSTRACT OF THE DISCLOSURE

A semiconductor package includes a lead frame having a displaced integral strap which is cupped out of a lead frame plane to provide a nest that receives a semiconductor chip electrically connected to an inner surface of the cupped strap. The semiconductor package further has a housing molded over and encapsulating the semiconductor chip with the frame such that a surface of the semiconductor chip facing away from the cupped strip is flush with or protrudes beyond a bottom of the housing.

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